

10 9 8 7 6 5 4 3 2 1

F

F

E

E

D

D

C

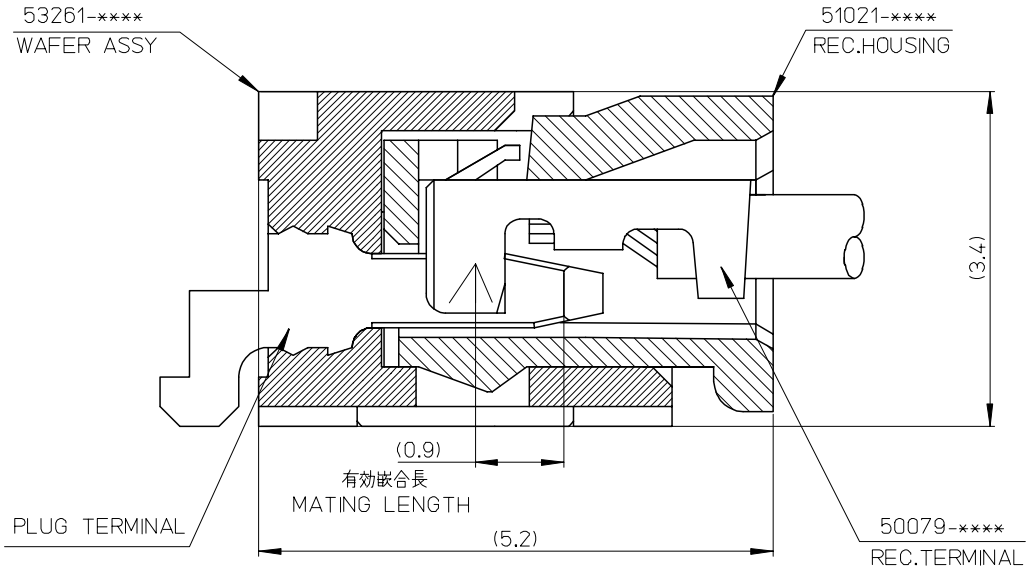
C

B

B

A

A



53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION			
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	DOCUMENT NO. SD-51021-002			
	ANGULAR	± --- °	MATERIAL NO. SEE CHART		SHEET NO. 1 OF 1			
0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9

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7

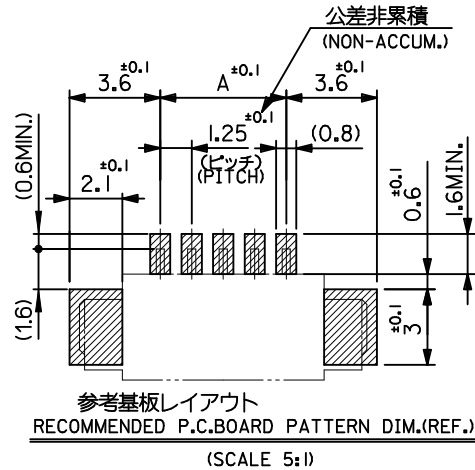
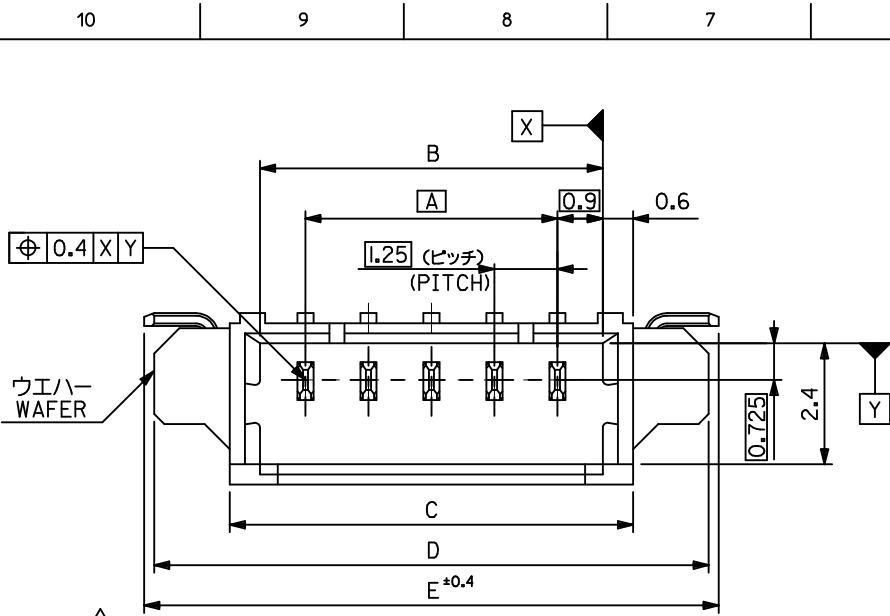
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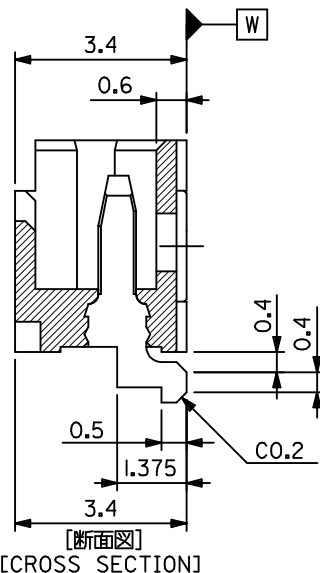
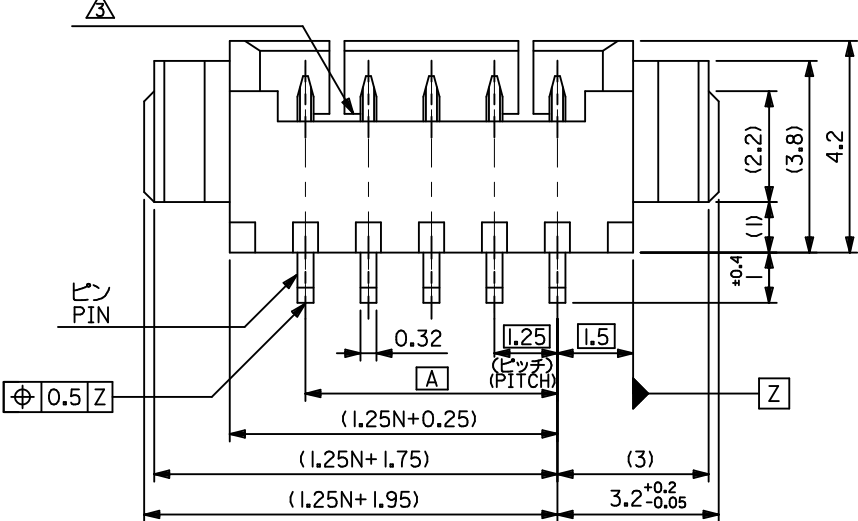
3

2

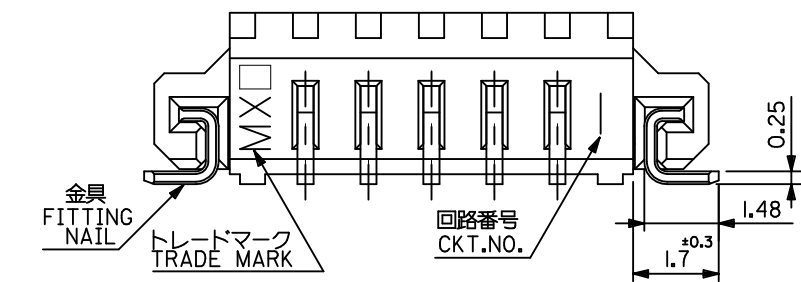


注記 NOTES

1. 嵌合相手: 51021 シリウス
MATES WITH: 51021 SERIES
2. 材質 MATERIAL
ウエハー: NYLON46, UL94V-0
ピン: リン青銅, 半田メッキ
PIN: PHOS-BRO., Sn-Pb(9:1) 3 μmMIN.
OVER Cu 1 μmMIN.
PLATING
金具: リン青銅, 半田メッキ
FITTING NAIL: PHOS-BRO., Sn-Pb(9:1) 2 μmMIN.
OVER Cu 1 μmMIN.
PLATING
- △ ロック窓は2、3極は1箇所、4極以上は2箇所とする。
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CKT. AND TWO PLACES FOR MORE THAN 3 CKT.
4. ソルダテール部のズレ量及び金具(補強板)のズレ量は基準面[W]に対し、上方向0.05 MAX.、下方向に0.1 MAX.とする。
OFFSET BETWEEN BASIS PLANE [W] TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM: UPPER SIDE: 0.05MAX. LOWER SIDE: 0.1MAX.



23.9	23.5	20.5	19.3	17.5	53261-1510	15
22.65	22.25	19.25	18.05	16.25	-1410	14
21.4	21	18	16.8	15	-1310	13
20.15	19.75	16.75	15.55	13.75	-1210	12
18.9	18.5	15.5	14.3	12.5	-1110	11
17.65	17.25	14.25	13.05	11.25	-1010	10
16.4	16	13	11.8	10	-0910	9
15.15	14.75	11.75	10.55	8.75	-0810	8
13.9	13.5	10.5	9.3	7.5	-0710	7
12.65	12.25	9.25	8.05	6.25	-0610	6
11.4	11	8	6.8	5	-0510	5
10.15	9.75	6.75	5.55	3.75	-0410	4
8.9	8.5	5.5	4.3	2.5	-0310	3
7.65	7.25	4.25	3.05	1.25	53261-0210	2
E	D	C	B	A	ENG. NO.	極数 CKT.



REVISED EC NO: J2012-1315 2012/04/17 DRWN: NITO 2012/04/17 CHKD: KASAKAWA 2012/04/17 APPR: YOITO 2012/04/26	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY NITO		DATE 2012/04/17		TITLE 1.25 WIRE TO BOARD WAFER ASS FOR SMT RIGHT ANGLE			
		10 OVER 30 UNDER	±0.25	CHECKED BY KASAKAWA		DATE 2012/04/17					
		30 OVER	±0.3	APPROVED BY YOITO		DATE 2012/04/26		MATERIAL NO. SEE DRAWING		DOCUMENT NO. SD-53261-054	
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					